Materials and Concepts for Textile Sensor Systems

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Christine Kallmayer © Fraunhofer IZM SIIT – System on Flex

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The Fraunhofer-Gesellschaft Locations in Germany

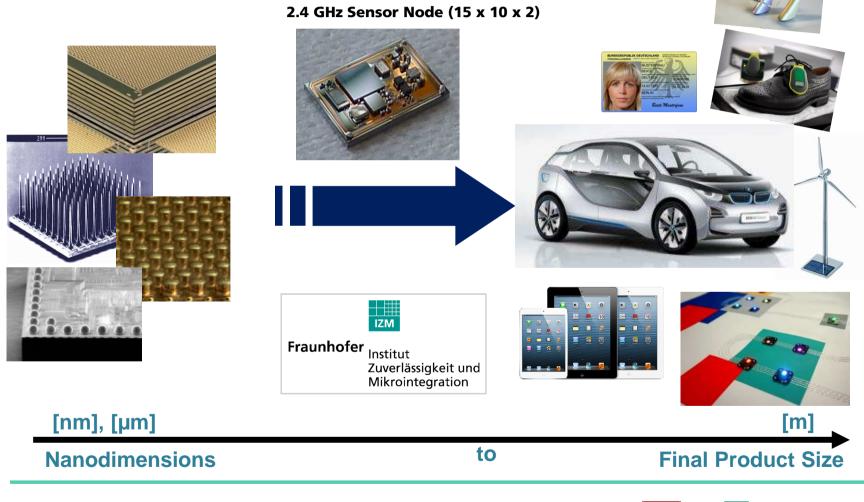
- 66 institutes and research units
- Nearly 24,000 staff
- More than €2 billion annual research budget totaling. Of this sum, around 1.7 billion euros is generated through contract research





Fraunhofer IZM's Mission: From Microelectronics and Microsystems towards Smart Systems

System Integration Technologies





Outline

- I. Introduction and Motivation
- II. Materials (conductors) for e-textiles
- III. Textile Circuit Manufacturing
- IV. Integration Technologies
- V. Sensor principles
- VI. Applications



Motivation

E-Textiles can overcome the disadvantages (limited acceptance in healthcare sector, limited accuracy, lacking validation, limited operation place e.g. only wrist) of current gadgets and much more.

E-Textiles advantages and opportunities

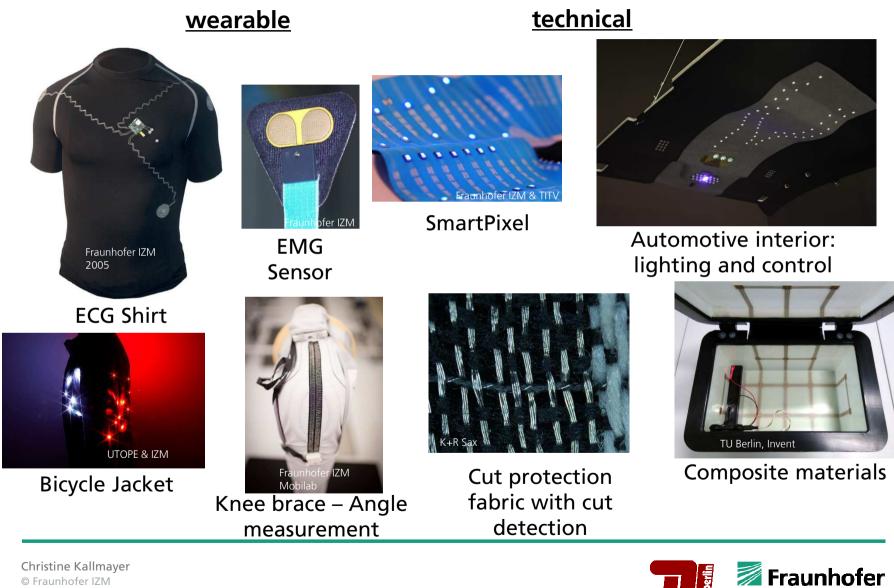
- Physically flexible and also stretchable
 - adapt to the shape of the human body
 - Low signal body monitoring possible (ECG, EMG)
 - Treatment of multiple areas on the body (TENS, EMS, heat, ligh
- Breathable
 - > ensures comfort
- Electronics as integral part of our everyday work cloth or outfit
- No size limitation
 - > Textile electronic circuits can be produced in large area or simultaneously/batch wise







E-Textile Applications Wearables vs. Technical Textiles



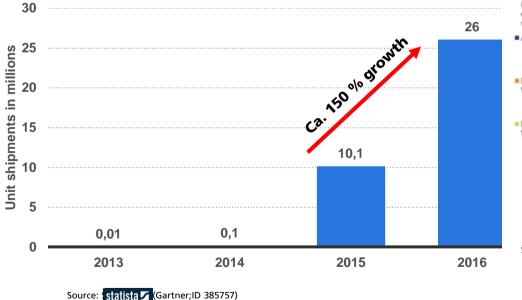
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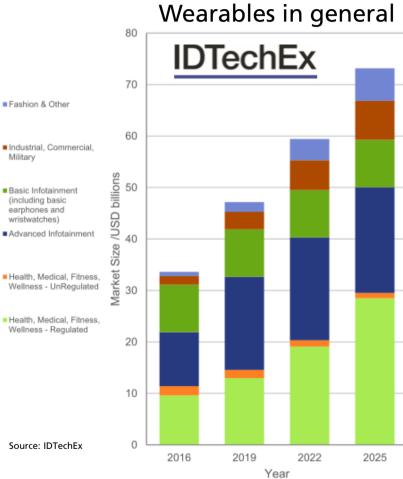
SIIT – System on Flex

Motivation (Market forecast, sections)

E-Textile products begin to penetrate the market (introduction phase), but it will need some time until acceptance.

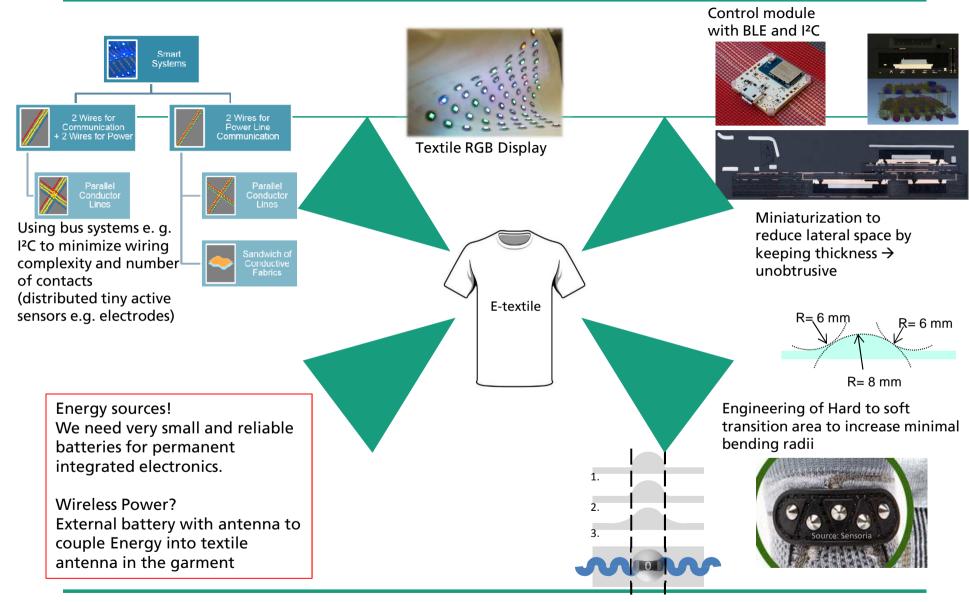
Forecast unit shipments of smart garments worldwide from 2013 to 2016 (in million units)





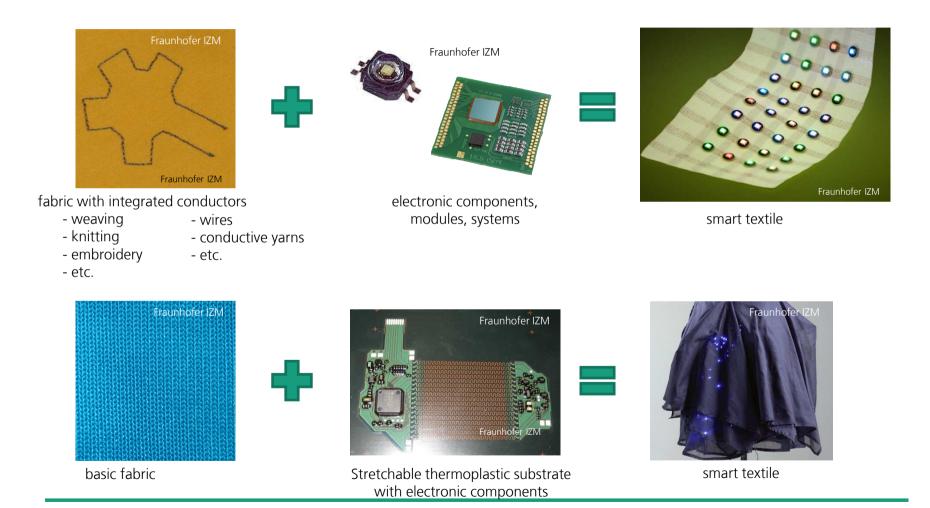


E-Textile Systems general observation





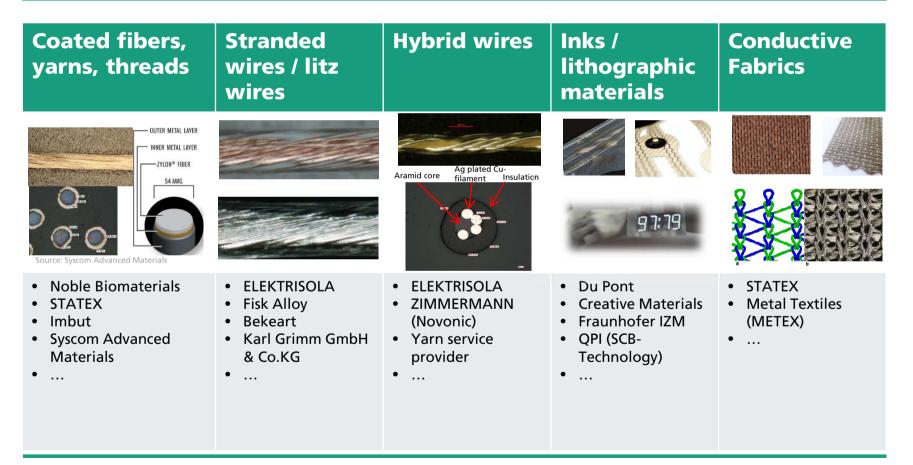
Textile-Integrated Electronic Systems





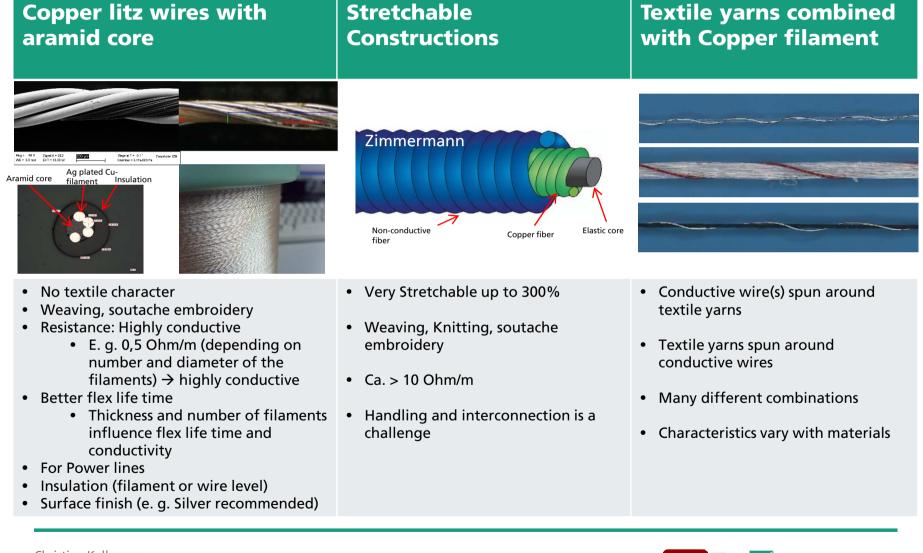
Materials (conductors) for e-textiles

There is a huge diversity of conductive materials for e-textile applications on the market.





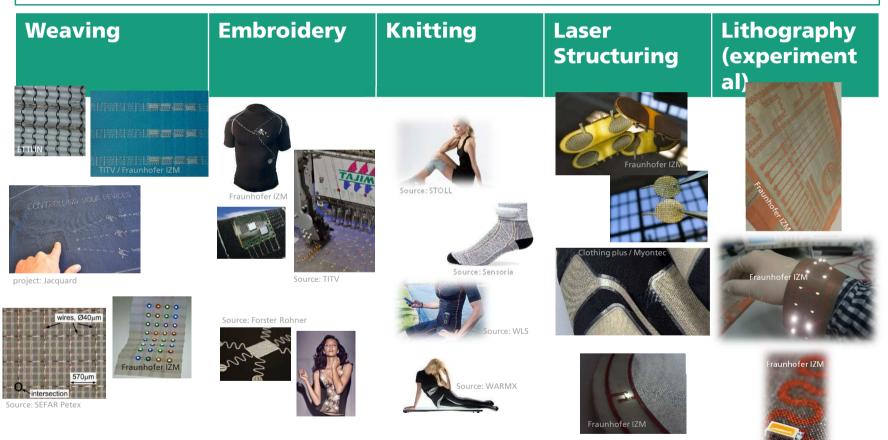
Materials: Hybrid wires





Textile Circuit Manufacturing

Conventional textile manufacturing processes can be used to generate conductive, textile circuits





Textile Circuit Manufacturing: Weaving

E-Textiles advantages and opportunities

- Large area production → multiple circuits at the same time with subsequent separation e. g. laser cutting
- With modern Jacquard weaving machines the location of the conductive thread can be controlled (in the backside/midle of the fabric → comes only to surface if needed e. g. to form an electrode or contact pad)
- Limited in freedom of circuit design → only warp/weft (leno is more flexible in 1 direction)



Stretchable conductive ribbon (AMOHR) e.g. lead (narrow weave technology)



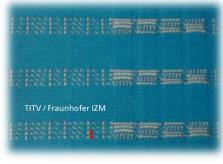
Jacquard weaved touch control panel (Google, TE Connectivity)

Coated fibers, yarns, threads

- Stranded wires, litz wires
- Hybrid wires
- Conducive inks
- Conductive fabrics



Leno weaved circuit (Conductors can be integrated in curved designs)



Jacquard weaved dual layer circuit with contact pads (pitch contact pads 1.27 mm)





Source: Donier :DORNIER EasyLeno®







Integration Technologies – General challenges

The textile industry and the electronics industry are not alike. Production facilities as well as products differ totally in many ways.



Textiles	Electronics
Limp, dimensional unstable, often (anisotropically) stretchable → handling and alignment of components is challenging	Rigid (FR4) or foil often with support material to guarantee dimensional stability during manufacturing
Manufacturing environment is often full of particles (fibers)	Clean manufacturing environment (particles lead to errors)
Strong degradation or melting of most textile materials above 200 °C can be expected \rightarrow contacting electronics is challenging	Peak temperature during reflow soldering above 250 °C (for std. solder)

- Suitable machinery to handle and manufacture e-textiles is still not available
- New technologies to enable a higher degree of integration are necessary (Customers want unobtrusive wearables, fully integrated)



Integration Technologies – A Selection of Technologies

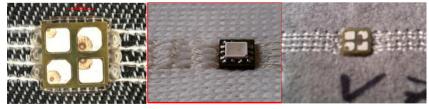




Integration Technologies: Adhesive Bonding (NCA)

Adhesive Bonding (NonConductiveAdhesive)

- Electronic modules are connected electrically and mechanically in 1 step
- Contacts are protected below the module
- Compatible to different fabrics and conductors
- Contacts are reliable in terms temperature, humidity and washing
- No solder / expensive conductive adhesive necessary
- Low-priced thermoplastic adhesive
- Temperature load during bonding process is high \rightarrow could be overcome with another reactive adhesive
- No machinery available for mass production \rightarrow handling textiles automatically for component attachment is challenging



Woven fabric with insulated hybrid wires

Knitted fabric with insulated hybrid wires

Embroidered fabric with hybrid wires



Bonded Stretchable

electronic lighting -

Accessible conductors

Insulated conductors

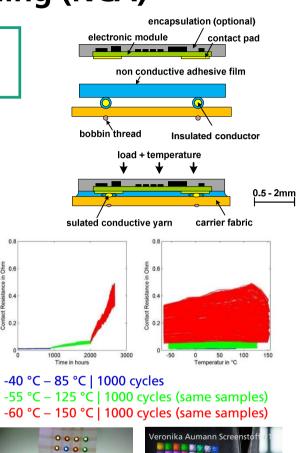
Cross section of a

contact

(thermoplastic insulation)

2-12 x 12 - 77 -

Sunvisor







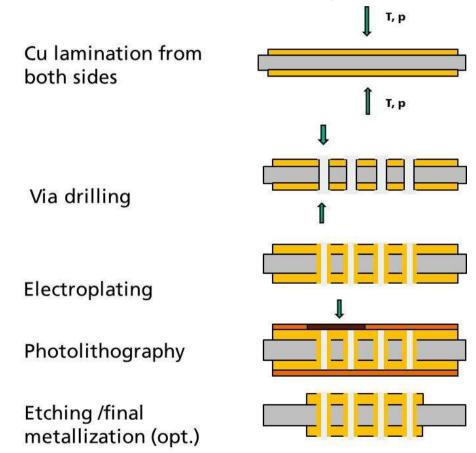
Textile display: Smart Pixel bonded onto Jaguard woven fabric

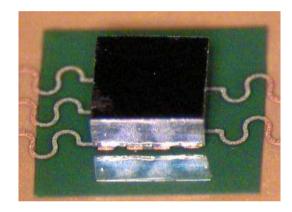


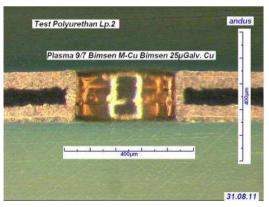


Stretchable Circuit Board

Base material: thermoplastic Polyurethane

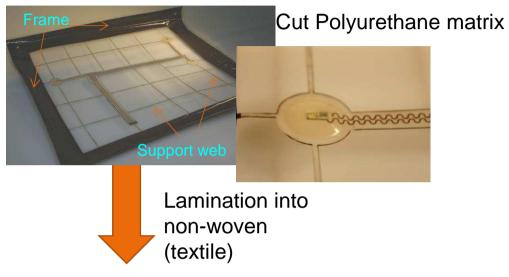








Stretchable Circuit Board – Integration into textiles



Embedding into a non-woven matrix

Lamination on Fabric





Electronics and fabric are combined in the last process step!

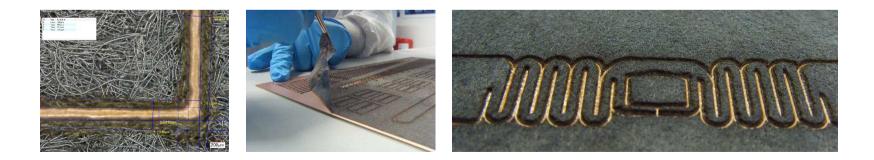




TexPCB Technology - ongoing



- New cost-effective, flexible conductive non-wovens for dynamic application in continuous operation (Substitution of conventional FPCBs)
- Resource-saving process technology for the production of textile circuit boards by Laser structuring and lamination processes
 - High adhesion force between TPU film and conductive fabric > 15N/mm after vacuum lamination achieved
 - Low contact resistance <500mΩ for NCA bonded FR-4 interposer onto textile pads</p>
 - Line pitch 250µm 550µm depending on chosen materials after laser structuring
- Reliable interconnection technology (polymer US welding, NCA bonding)





Measurement Principles for Textile Sensors

Principle	Technology	Damage	Strain	Pressure	Humidity
Resistance	Printed woven embroidered	Х	Х	Х	Х
Capacitance	Printed, SCB Woven		Х	Х	Х
Inductance	Woven Embroidered		Х	Х	

Polymer based sensors typically show:

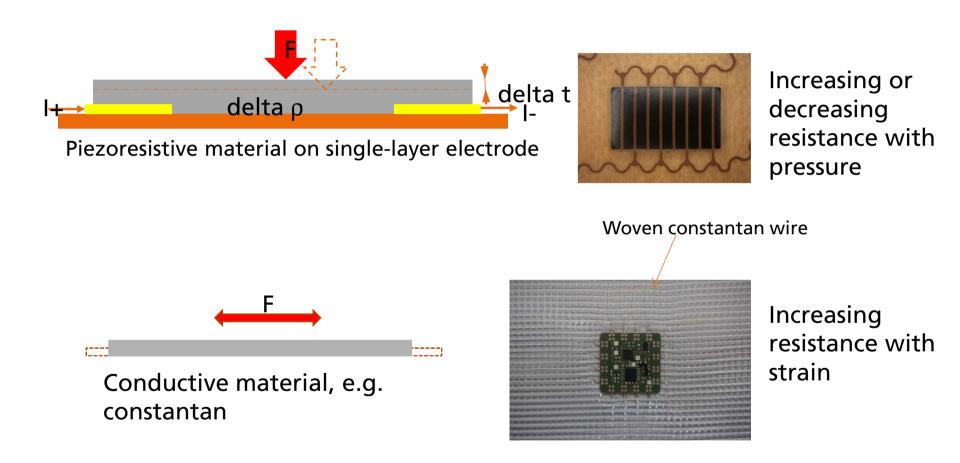
- hystheresis
- temperature dependance
- humidity dependance
- drift

ha ha

Conventional sensors have to be integrated in textiles for high performance!

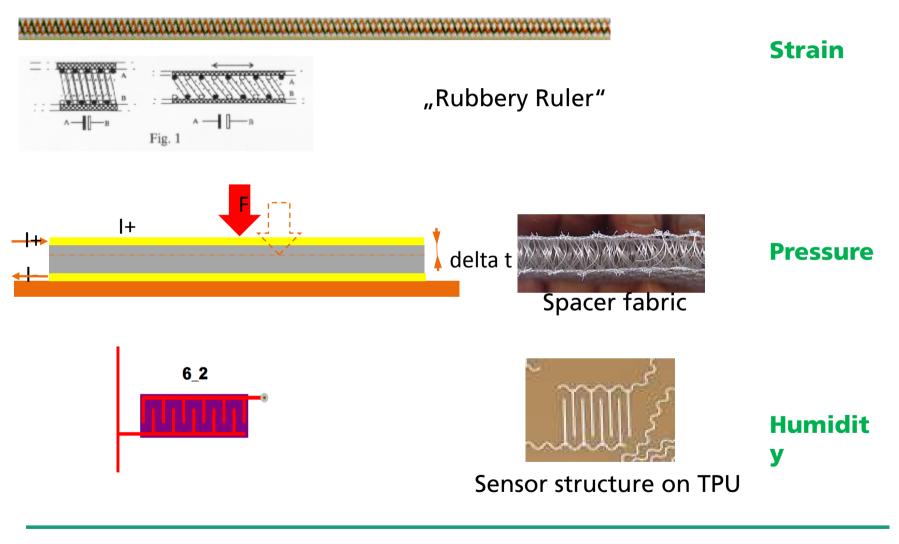


Sensor Principles: Resistive Sensors



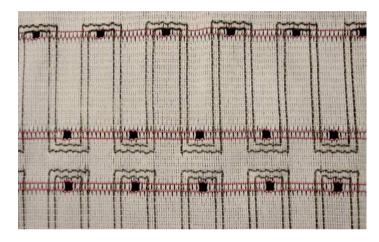


Sensor Principles: Capacitive Sensors



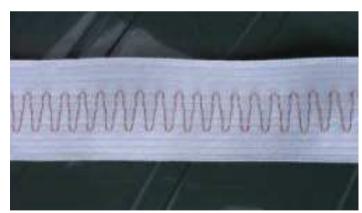


Sensor Principles: Inductive Sensors



Measurement of varying coupling factor between parellel woven inductivities

Strain / pressure



Measurement of varying inductance of meander structure (woven or embroidered)

Strain



Strain Measurement MoTex - MOnitoring TEXtiles

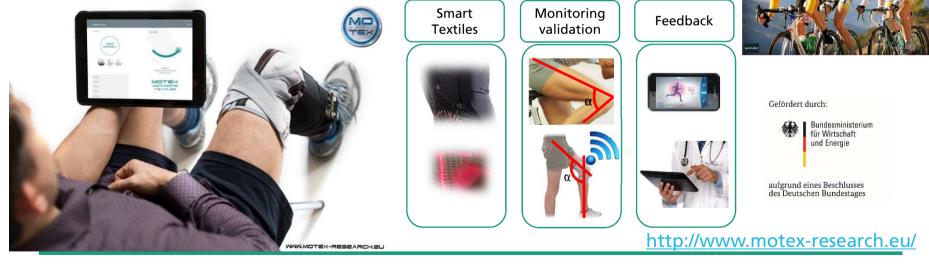
Smart Textile based knee brace for accurate measurement/monitoring of the knee angles

Application fields:

- Healthcare/medical: monitoring of rehabilitation trajectory of patients with total knee arthroplasty)
- Sport: monitoring of knee angles for cyclists to avoid wrong position which could lead to knee problems

Data will be collected by a Smartphone and transferred to

a cloud where it can be analyzed from doctors or coaches



C E N T E X B E L





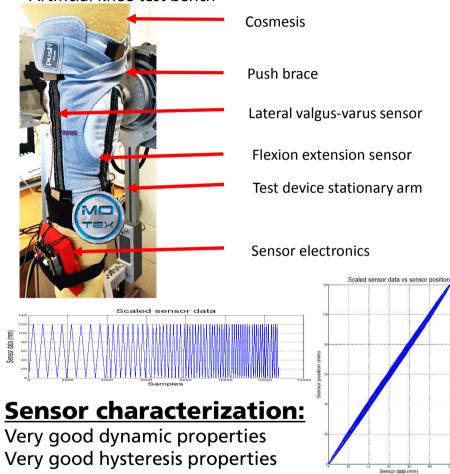


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FORSCHUNGS textil Fraunhofer

MOTEX MOnitoring TEXtiles

Artificial knee test bench



Force or way controlled cyclic



<u>Reliability:</u>

100k Stretch cycles at 50% stretch passed Validated by Electrical, optical and x-ray inspection

pection



Damage DetectioneCargoBag Extended Safety Features for Green Urban Mobility



Christine Kallmayer © Fraunhofer IZM SIIT – System on Flex 26





Technische Univerzität Berlin Forschungsschwerpunkt Technologien der Mikroperipherik





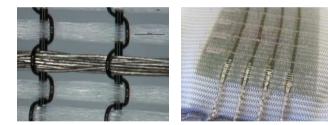
Damage Detection AlarmTextil – Large Area Woven Alarm Device

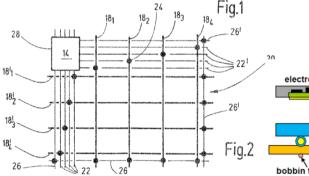
- Woven conductive pattern (repeatable) in Polyester fabric
- Electronic module with embedded components assembled with nonconductive adhesive
- Basic structure detects damage at 16 Positionen
- Bus system enables free combinations of basic cell
- Integration in walls, floors, tarpaulins

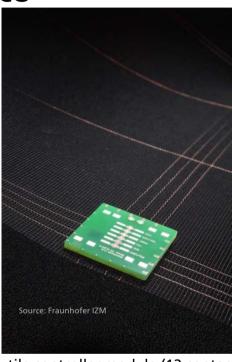


Bank robbery Berlin, Januar 2013

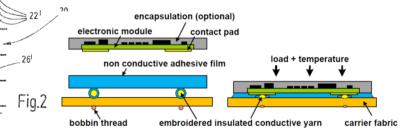
Quelle: Focus online; dpa/Paul Zinken







Alarm Textile controller module (12 contacts)





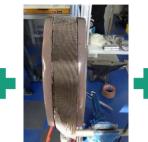
Strain Measurement Composite embedded electronics – pasta Project



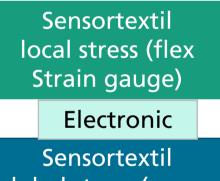


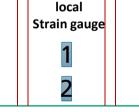
Woven Sensor fabric + electronics

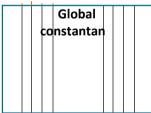
Structural carbon and basalt layers



Shaping and stacking all layers









Epoxy injection under vaccuum



Testing of electronics and sensors



ta

Final carbon blade



Prosthesis stem

Knee joint

Carbon blade

Final C-Leg with periphery (child)

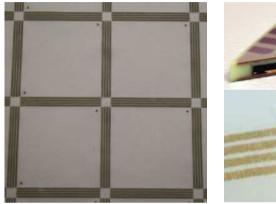


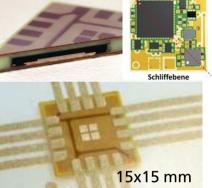






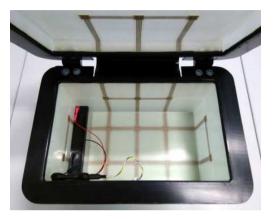
MoMiTeX: Composite Box for Battery Protection and Monitoring





Embedding in fibre reinforced Polymer

Forming of battery case



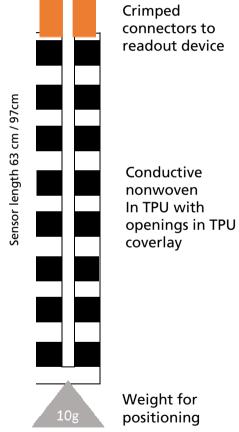


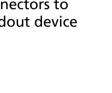
INVENT

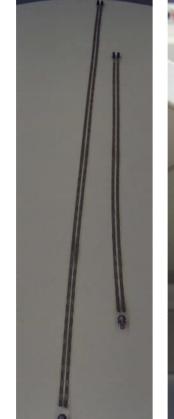
- Number of sensors: 20
- Temperature sensor
- 3 axis accelerometer
- Damage detection and localization
- Self-Test of sensors
- Temperature range: -25 bis + 85°C
- Dimensions of sensor modules: max. 15 x15 x 2mm
- Printed bus structures
- Embedding of bus and modules in composite at high pressure/ temperature



TexPCB Textile Humidity Sensor







Prototype



Readout device







Conclusion

 Different simple textile sensor concepts allow the measurement of pressure, strain, humidity as well as the detection of damage

 Polymer and textile sensors are cost effective but show lower performance -> for high requirements conventional sensors have to be integrated

 The applications range from medical products to structural health monitoring in composite materials -> broad range of requirements

 Materials and technologies has already been developed to fulfill the various requirements but there are no standard solutions



Thank you for your Attention

ALL SHINY LIGHTS - LIGHT CURTAIN